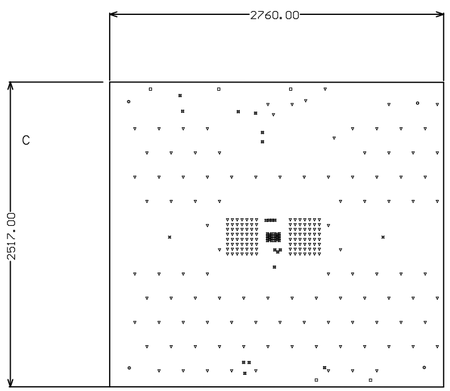

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊠	40	8,00mil (0,203mm)	PTH	Round	Top Layer - Bottom Layer	
▽	218	15,00mil (0,381mm)	PTH	Round	Top Layer - Bottom Layer	
□	5	51,97mil (1,320mm)	PTH	Round	Top Layer - Bottom Layer	
✪	4	145,00mil (3,683mm)	PTH	Round	Top Layer - Bottom Layer	
⌘	2	263,78mil (6,700mm)	NPTH	Round	Top Layer - Bottom Layer	
	269 Total					

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		2.80mil		
	Dielectric1	FR-4	17.00mil	4.2	
2	Signal Layer 1		2.80mil		
	Dielectric 2	FR-4	17.00mil	4.2	
3	Signal Layer 2		2.80mil		
	Dielectric 3	FR-4	17.00mil	4.2	
4	Bottom Layer		2.80mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.127 mm
MIN. VIA PAD SIZE: 18 MIL
MINIMUM ANNULAR RING 5 MIL EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
FR-408 X FR-4 High Tg OTHER
THICKNESS: X 63 MIL (1.6mm) +/-10% OTHER
TOLERANCE: X ANSI IPC-6012 TYPE 3 CLASS 2
OTHER +/-
BOW & TWIST: X ANSI IPC-6012 TYPE 3 CLASS 2
OTHER +/-

DRILLING:
REFERENCE: X AS SHOWN X NC_DRILL FILES
PTH COPPER THICKNESS: X 20-30 um OTHER

BOARD FINISH:
SILKSCREEN: X TOP X BOTTOM
SILKSCREEN COLOR: X WHITE OTHER
SOLDER RESIST COLOR: X GREEN OTHER
X MATTE SEMI-GLOSS

SURFACE FINISH: X IMMERSION GOLD (ENIG) ENEPIG
IMM. TIN/SILVER OR EQUIV OTHER

ARRAY/PANEL: CUT AND TRIM PER M1 BOARD OUTLINE
N.C. ROUTE X V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
X ANSI IPC-A-600F CLASS -> 1 X 2 3
X RoHS OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: NO
BARE BOARD ELEC. TEST: X NONE REQUIRED PER ORDER
No VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
No VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
LAYER 2 & 3 (INNER LAYERS) 17 MIL WIDE, XX MIL SPACE
TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE:
INA750-INA751EVM

DESIGNED FOR:
Public Release

FILE NAME:
SENS142A1.PcbDoc

ENGINEER: G Zhou
LAYOUT BY: G Zhou
SCALE: 1.00
ALTIUM DESIGNER VERSION: 23.1.1.15

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = [redacted]ions
PLOT NAME = Fabrication Drawing

BOARD #: SENS142 REV: A1 SUN REV: Not in version control
TID #: N/A
GENERATED : 10/17/2024 10:23:05 PM TEXAS INSTRUMENTS

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